

## N- and P-Channel 20 V (D-S) MOSFET

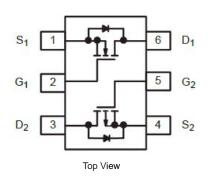
PRODUCT SUMMARY					
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)		
N-Channel	20	$0.270 \text{ at V}_{GS} = 4.5 \text{ V}$	0.60		
		0.410 at V <sub>GS</sub> = 2.5 V	0.55		
P-Channel	- 20	0.660 at V <sub>GS</sub> = - 4.5 V	- 0.30		
		0.840 at V <sub>GS</sub> = - 2.5 V	- 0.25		

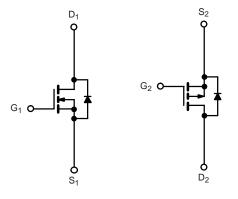
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
  Compliant to RoHS Directive 2002/95/EC









N-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted							
Parameter		Symbol	N-Channel	P-Channel	Unit		
Drain-Source Voltage		$V_{DS}$	20	- 20	V		
Gate-Source Voltage		$V_{GS}$	± 20	± 20	V		
Continuous Drain Current (T <sub>.I</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 25 °C	I <sub>D</sub>	0.6	- 0.3	A		
Continuous Drain Current (1 j = 150 °C)	T <sub>A</sub> = 70 °C		0.55	- 0.25			
Pulsed Drain Current		I <sub>DM</sub>	3	- 2	A		
Continuous Source Current (Diode Conduction) <sup>a, b</sup>		I <sub>S</sub>	1.05	- 1.05			
Marrian Parran Disain ation 8, b	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.15		W		
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 70 °C	, D	0.73				
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Naccional languing to Ambigueta	t ≤ 5 s	- R <sub>thJA</sub>	93	110	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		130	150		
Maximum Junction-to-Lead	Steady State	$R_{thJL}$	75	90		

a. Surface Mounted on FR4 board.

b.  $t \le 5$  s.



Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit	
Static	•							
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ N-Ch		0.7			.,	
		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	P-Ch	- 0.8			V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	N-Ch			± 100	nA	
			P-Ch			± 100		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V	N-Ch			1		
		$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$ N				- 1	μA	
						5		
		V <sub>DS</sub> = - 24 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	P-Ch			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	3.7			А	
		$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	- 3				
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, I_D = 0.6 \text{ A}$	N-Ch		0.410			
		$V_{GS} = -2.5 \text{ V}, I_D = -0.3 \text{A}$			0.840			
		$V_{GS} = 4.5 \text{ V}, I_D = 0.6A$	N-Ch		0.270		Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 0.3 A	P-Ch		0.660			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	N-Ch		4.3		_	
		V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 1.8 A	P-Ch		2.4		S	
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = 1.05 A, V <sub>GS</sub> = 0 V	N-Ch		0.81	1.10	V	
		I <sub>S</sub> = - 1.05 A, V <sub>GS</sub> = 0 V	P-Ch		- 0.83	- 1.10		
Dynamic <sup>b</sup>								
Total Gate Charge	0		N-Ch		2.1	3.2		
Total Gate Charge	Qg	N-Channel $V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 1.8 \text{ A}$	P-Ch		2.4	3.6	nC	
Gate-Source Charge	Q <sub>gs</sub>	VDS = 13 V, VGS = 3 V, ID = 1.0 A	N-Ch		0.7			
		P-Channel	P-Ch		0.9			
Gate-Drain Charge	$Q_{qd}$	$V_{DS} = -15 \text{ V}, V_{GS} = -5 \text{ V}, I_{D} = -1.8 \text{ A}$	N-Ch		0.7			
	9-		P-Ch	0.5	0.8	0.4		
Gate Resistance	$R_g$		N-Ch P-Ch	0.5 3		2.4 11	Ω	
Turn-On Delay Time Rise Time	t <sub>d(on)</sub>		N-Ch		7	11		
		N-Channel	P-Ch		8	12		
		$V_{DD} = 15 \text{ V}, R_{L} = 15 \Omega$	N-Ch		9	14		
		$I_D \cong 1 \text{ A, V}_{GEN} = 10 \text{ V, R}_g = 6 \Omega$	P-Ch		12	18		
Turn-Off Delay Time	t <sub>d(off)</sub>	P-Channel	N-Ch		13	20		
		$V_{DD} = -15 \text{ V}, R_L = 15 \Omega$	P-Ch		12	18	ns	
Fall Time	t <sub>f</sub>	$I_D \cong -1$ A, $V_{GEN} = -10$ V, $R_g = 6$ $\Omega$	N-Ch		5	8		
		-	P-Ch		7	11		
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	$I_F = 1.05 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$ N-Ch $I_F = -1.05 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$ P-Ch			35	60		
					30	60		

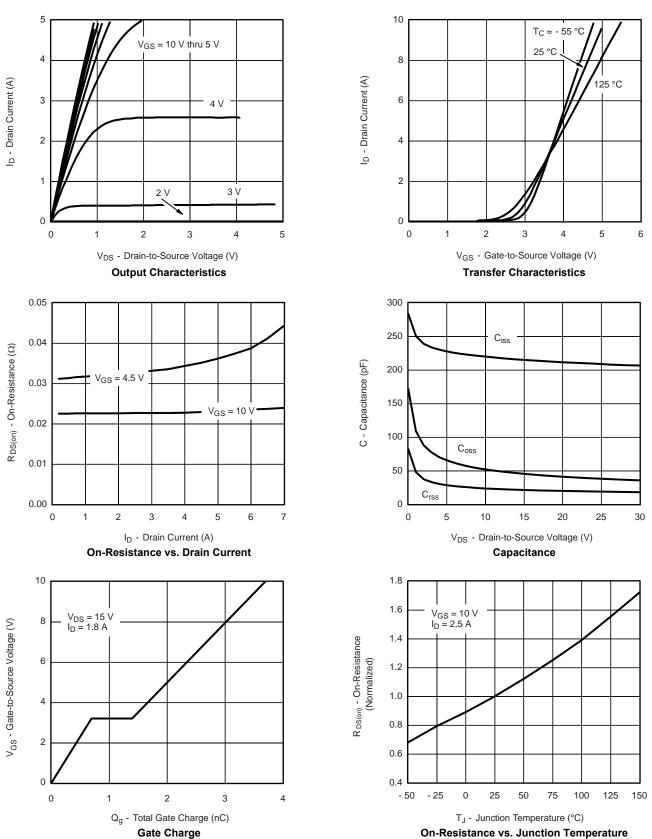
#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

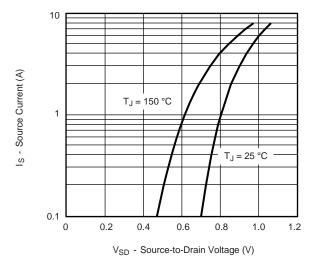


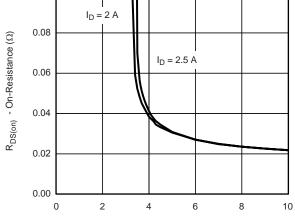
### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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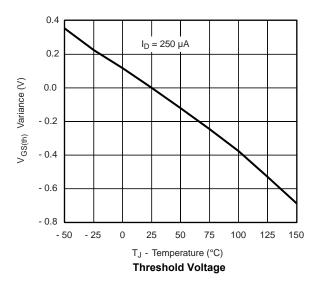




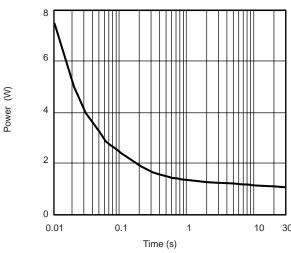
0.10

V<sub>GS</sub> - Gate-to-Source Voltage (V)

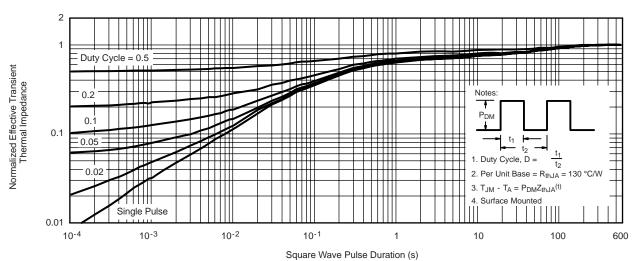




On-Resistance vs. Gate-to-Source Voltage



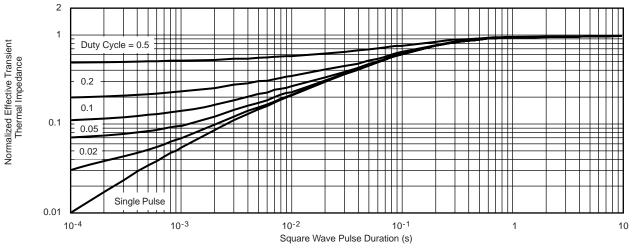
Single Pulse Power (Junction-to-Ambient)



Normalized Thermal Transient Impedance, Junction-to-Ambient

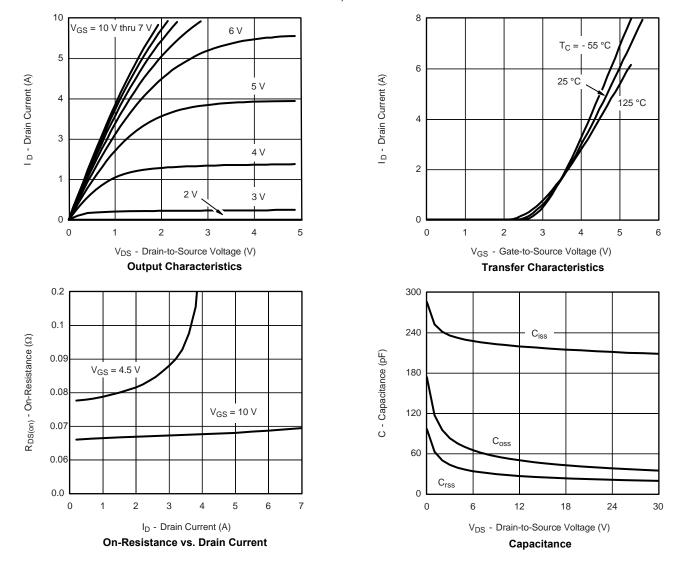


#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



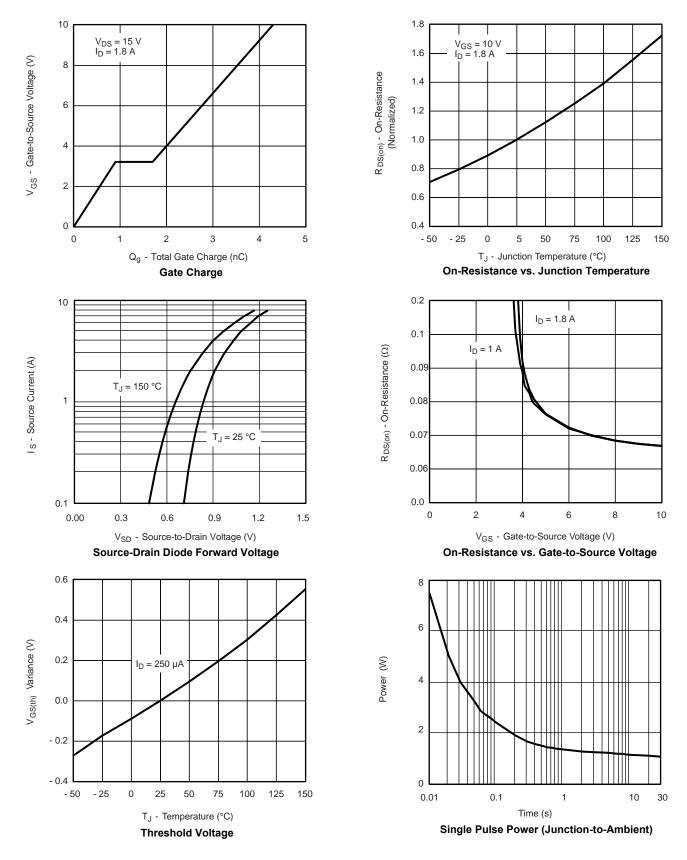
Normalized Thermal Transient Impedance, Junction-to-Foot

#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



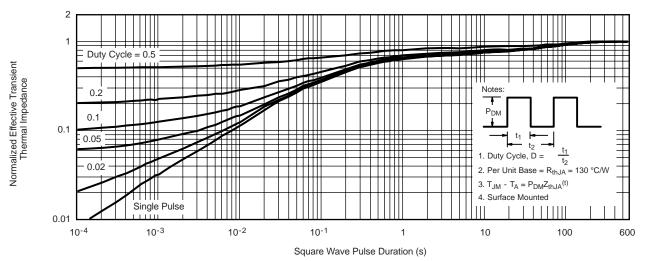


#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

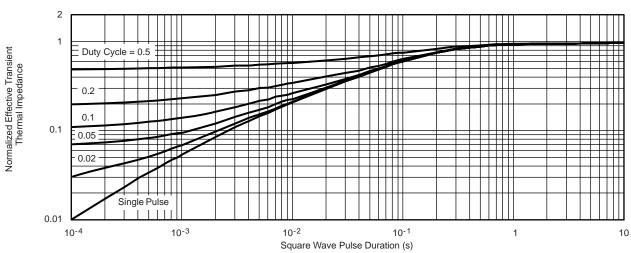




### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



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